



March 4, 2024,

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RE

Declaration Letter

RE: WCM-Tx1

FCC: L2C0091TR

IC: 3432A-0091TR

HVIN original (PV1): 1356 0618 / 1356 0619 / 1356 0620 / 1356 0621

HVIN updated (PV2): 1356 4197 / 1356 4198 / 1356 4199 / 1356 4200

The GM Wireless Charging Module **WCM_tx1** has been updated from a PV1 to PV2 and we are seeking a FCC and ISED class 2 permissive change.

These differences are;

1) HW Change - Antenna PCB

- Layers 3 & 4 swapped to improve PCB flatness / manufacturing quality
- No copper change

Emissions and immunity evaluated by 3rd party: no change from PV1 to PV2

2) HW Change – BOM change

- Tuning of NFC matching to compensate for slight change in NFC antenna impedance due to antenna board layer swap
- Populate C181 100uF capacitor on output of 5V DC converter
- BOM change only, no layout change

Emissions and immunity evaluated by 3rd party: no change from PV1 to PV2



3) HW Change – New circuit

- New circuit added for receiver demodulation

Emissions and immunity evaluated by 3rd party: no change from PV1 to PV2

4) HW Change – New circuit

- New level shifter circuit to monitor QI_SW1 at micro

Emissions and immunity evaluated by 3rd party: no change from PV1 to PV2

5) HW Change – BOM change

- Component value changes to improve scaling of signals to be read by microcontroller ADC
- No layout change

Emissions and immunity evaluated by 3rd party: no change from PV1 to PV2

EMC Comparison PV1 → PV2

Background

- Based on the changes in hardware from PV1 to PV2, no emissions impact is expected
- Emission and immunity testing was performed by a 3rd party to verify they are equivalent in PV2 vs PV1

Sincerely,

A handwritten signature in black ink, appearing to read "John Gettel".

John Gettel